



PRE-RELEASE VERSION (FDIS)

Field device integration (FDI) – Part 115-2: Profiles – Modbus-RTU

INTERNATIONAL
ELECTROTECHNICAL
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TITLE:

Field Device Integration (FDI) – Part 115-2: Profiles – Modbus-RTU

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NOTE FROM TC/SC OFFICERS:

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD DEVICE INTEGRATION (FDI) –

Part 115-2: Profiles – Modbus-RTU

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International Standard IEC 62769-115-2 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

FCG_TS62769-115-2_Profiles_PSD ModbusRTU_1.1.0.4, a specification of the FieldComm Group, PROFIBUS Nutzerorganisation e. V., OPC Foundation and FDT Group, has served as a basis for the elaboration of this standard.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
65E/XX/FDIS	65E/XX/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

FIELD DEVICE INTEGRATION (FDI) –

Part 115-2: Profiles – Modbus-RTU

1 Scope

This part of IEC 62769 defines the protocol-specific definitions (PSDs) as defined in IEC 62769-7 on generic protocol extensions for the Modbus®¹-RTU protocol in accordance with CPF 15 in IEC 61784-2.

2 Normative References

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61784-1, *Industrial communication networks – Profiles – Part 1: Fieldbus profiles*

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 62541-100, *OPC Unified Architecture – Part 100: Device Interface*

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

IEC 62769-4, *Field Device Integration (FDI) – Part 4: FDI Packages*

IEC 62769-5, *Field Device Integration (FDI) – Part 5: FDI Information Model*

IEC 62769-7, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*

MOD06, *Modbus.org: MODBUS over serial line specification and implementation guide V1.02*

MOD12, *Modbus.org: MODBUS APPLICATION PROTOCOL SPECIFICATION, V1.1b3*

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